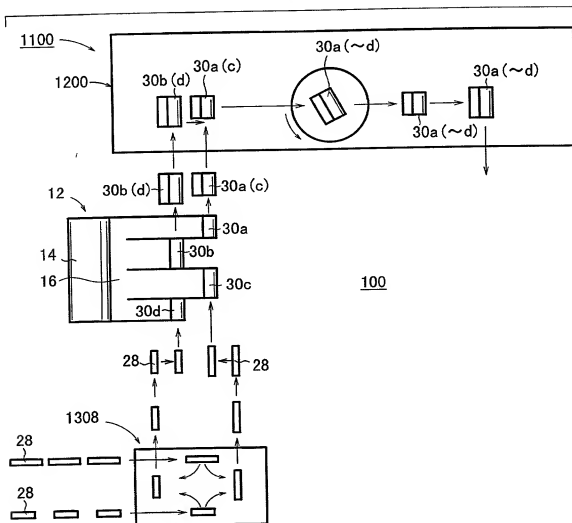


FIG. 1



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The diagram illustrates a complex multi-layer PCB assembly. At the top, a large rectangular component labeled 12 is shown, which includes a section 16 and a series of vertical strips or vias labeled ME10, 30a, 30a', 30b, 30b', 30c, 30c', 30d, and 30d'. Arrows indicate connections from these strips to other parts of the assembly. Below this, there are several vertical columns of components. On the left, two horizontal bars labeled 28 are connected to a larger block 1308 at the bottom. In the center, there are four vertical columns, each containing a component labeled 28. These are interconnected by various lines and labels: 1102B, ME7, 1306, 1318, ME4, 1304, 1300, 1316, ME5, 1302, ME6, ME8, ME9, ME1, 1326, 1328, 1322, 1314, and 1320. The rightmost column shows a stack of components including 102A, 10, ME9, 30c', 30d', and 1302. The overall layout suggests a dense, multi-functional electronic device.

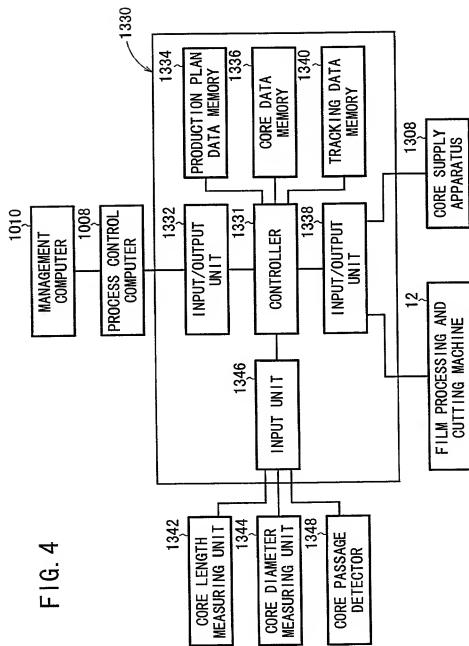
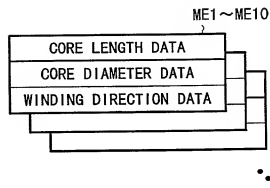
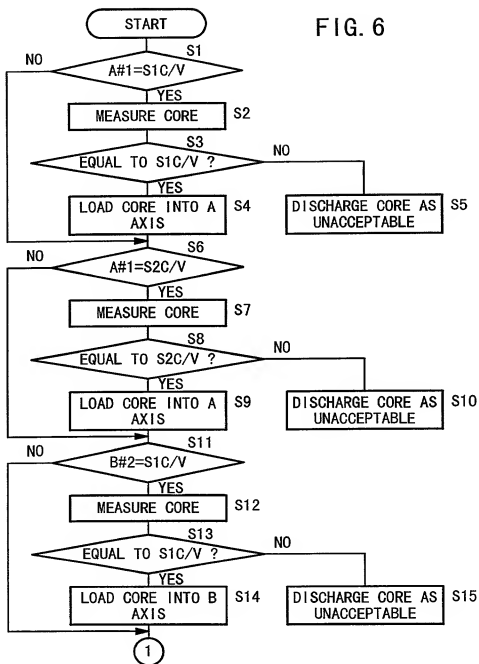


FIG. 5



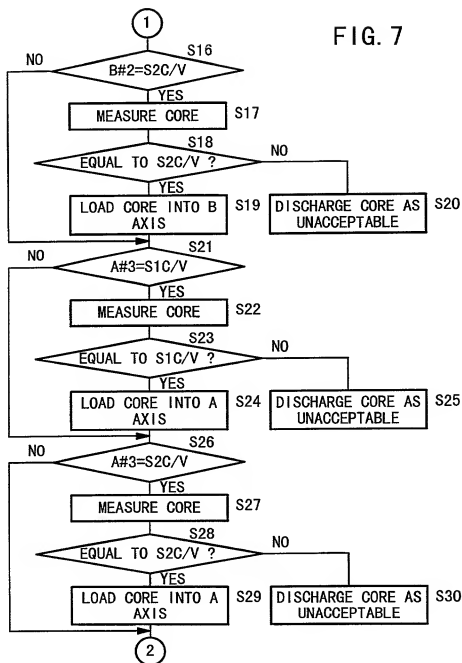
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FIG. 6



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FIG. 7



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FIG. 8

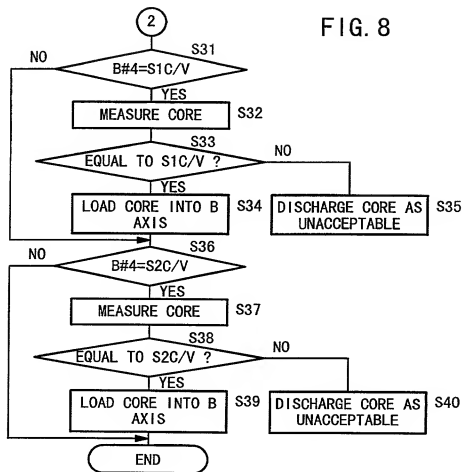
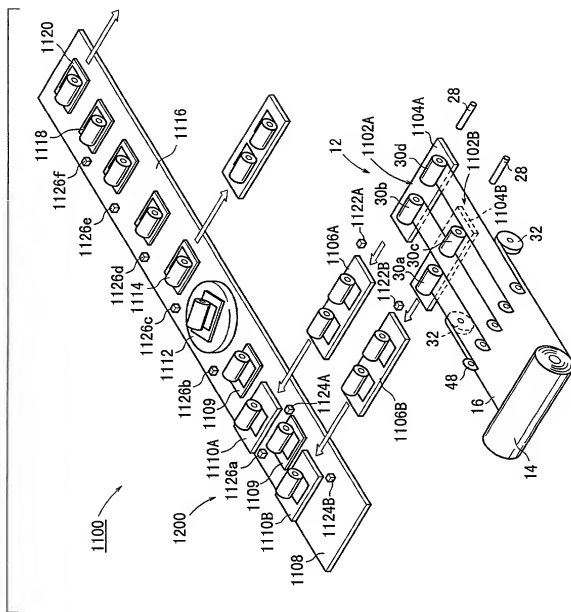


FIG. 9

FIG. 9



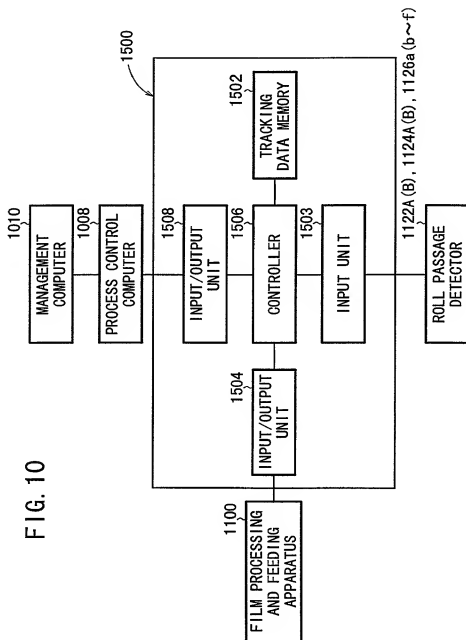
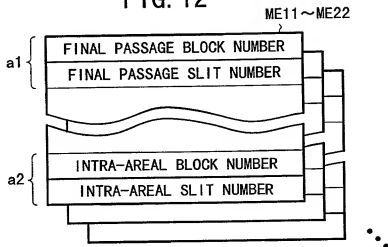


FIG. 12



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FIG. 13

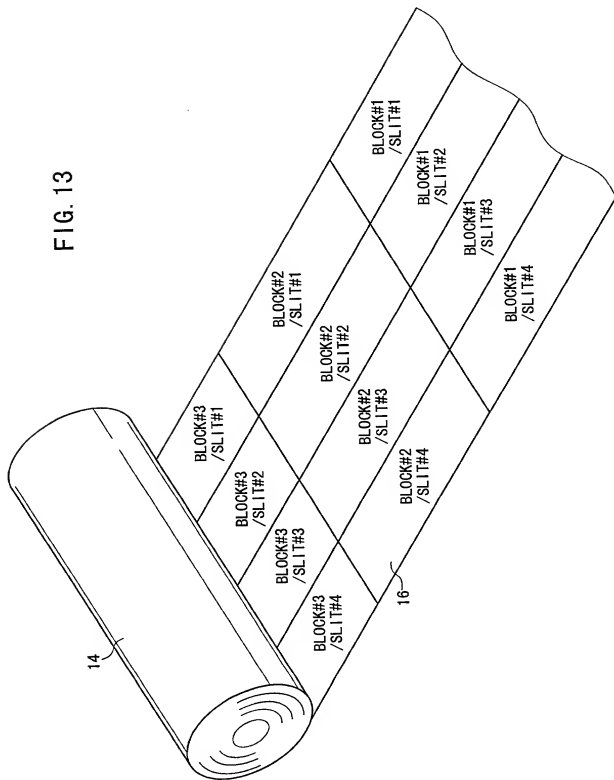
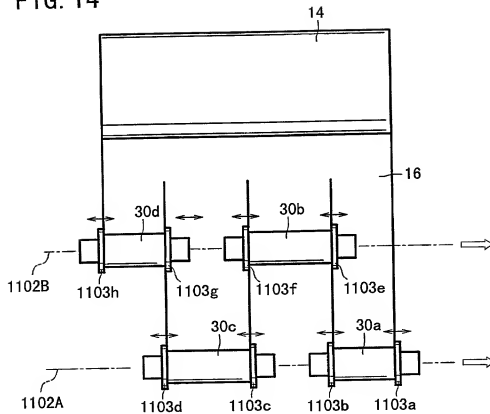
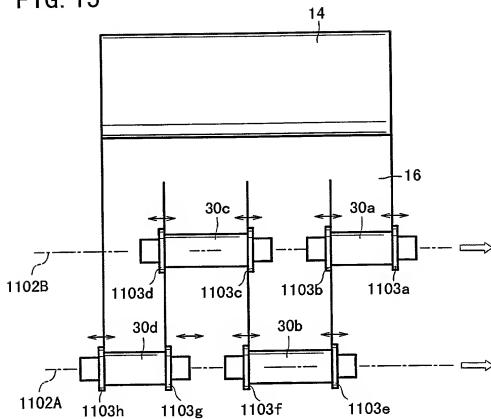


FIG. 14



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FIG. 15



10014507.12401

FIG. 16

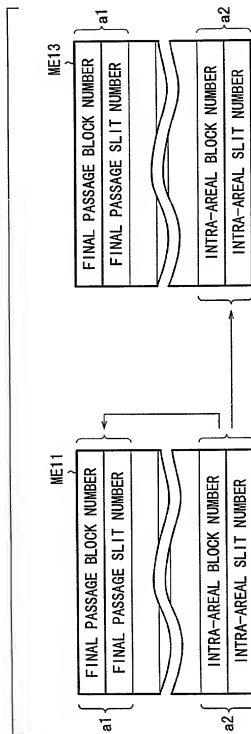
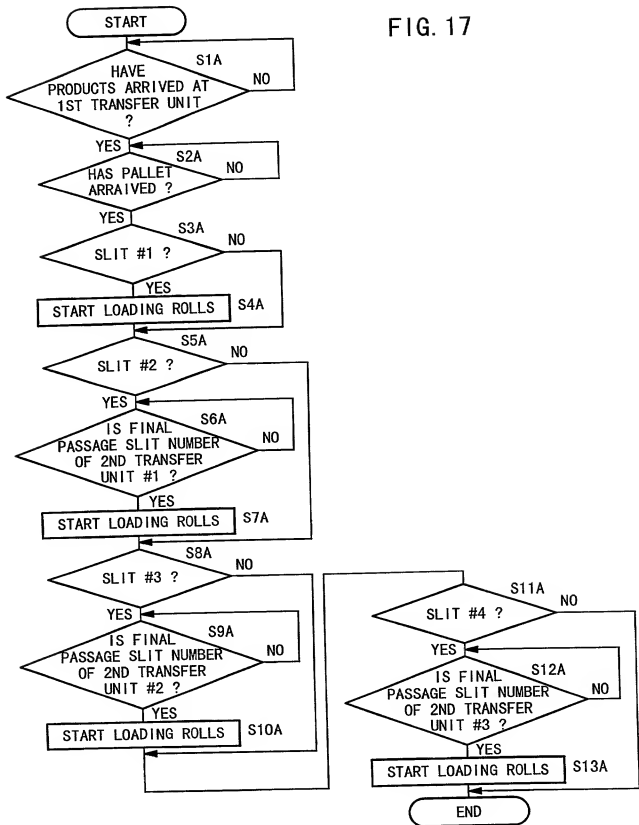
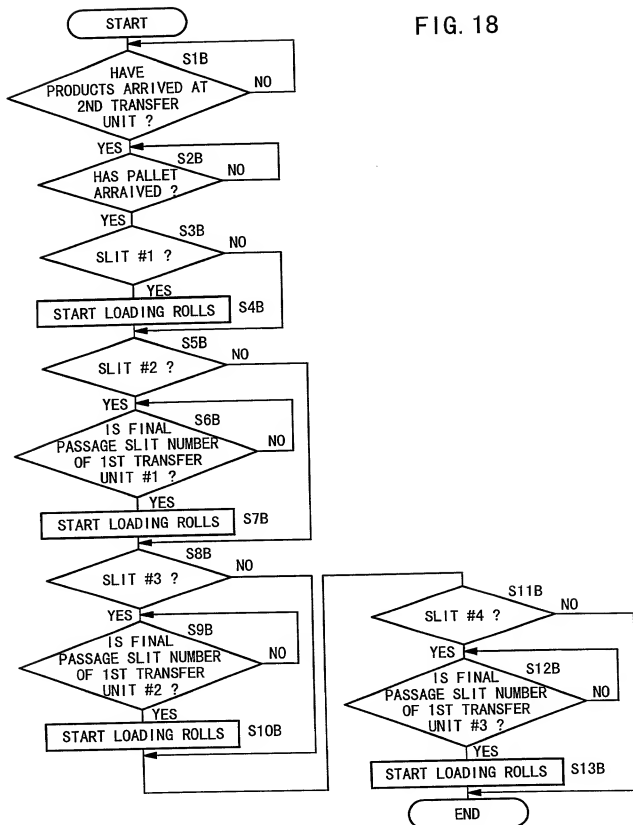


FIG. 17



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FIG. 18



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